

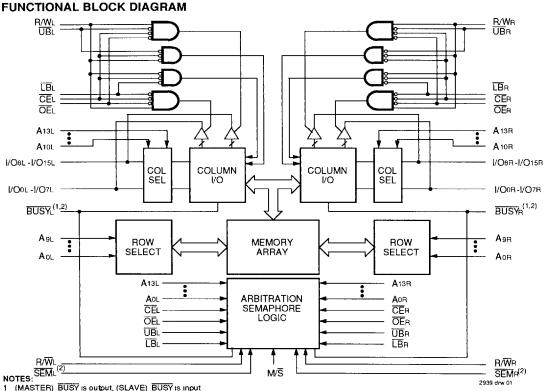
HIGH-SPEED 16K x 16 DUAL-PORT STATIC RAM

PRELIMINARY IDT7026S/L

FEATURES:

- · True Dual-Ported memory cells which allow simultaneous reads of the same memory location
- High-speed access
 - Military: 35/45/55/70ns (max.)
 - Commercial: 25/35/45/55ns (max.)
- Low-power operation
 - IDT7026S
 - Active: 750mW (typ.)
 - Standby: 5mW (typ.)
 - IDT7026L
 - Active: 750mW (typ.)
 - Standby: 1mW (typ.)
- · Separate upper-byte and lower-byte control for

- multiplexed bus compatibility
- · IDT7026 easily expands data bus width to 32 bits or more using the Master/Slave select when cascading more than one device
- M/S = H for BUSY output flag on Master $M/\overline{S} = L$ for \overline{BUSY} input on Slave
- · On-chip port arbitration logic
- Full on-chip hardware support of semaphore signaling between ports
- Fully asynchronous operation from either port
- TTL-compatible, single 5V (±10%) power supply
- Available in 84-pin PGA, and PLCC
- Industrial temperature range (-40°C to +85°C) is available, tested to military electrical specifications



- BUSY outputs are non-tri-stated push-pull

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MILITARY AND COMMERCIAL TEMPERATURE RANGES

NOVEMBER 1993

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DSC1082/1

DESCRIPTION:

The IDT7026 is a high-speed 16K x 16 Dual-Port Static RAM. The IDT7026 is designed to be used as a stand-alone 256K-bit Dual-Port RAM or as a combination MASTER/SLAVE Dual-Port RAM for 32-bit-or-more word systems. Using the IDT MASTER/SLAVE Dual-Port RAM approach in 32-bit or wider memory system applications results in full-speed, error-free operation without the need for additional discrete logic.

This device provides two independent ports with separate control, address, and I/O pins that permit independent, asynchronous access for reads or writes to any location in

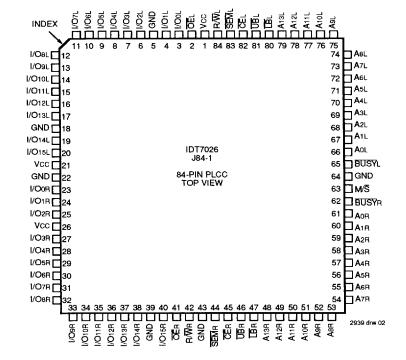
memory. An automatic power down feature controlled by $\overline{\text{CE}}$ permits the on-chip circuitry of each port to enter a very low standby power mode.

Fabricated using IDT's CMOS high-performance technology, these devices typically operate on only 750mW of power.

The IDT7026 is packaged in a ceramic 84-pin PGA, an 84-pin quad flatpack, and PLCC. Military grade product is manufactured in compliance with the latest revision of MIL-STD-883, Class B, making it ideally suited to military temperature applications demanding the highest level of performance and reliability.

INTEGRATED DEVICE

PIN CONFIGURATIONS



	63	61	60	58	55	54	51	48	46	45	42
11	I/O7L	I/O5L	I/O4L	I/O2L	1/OoL	ŌĒL	SEML	LBL	A12L	A11L	AsL
	66	64	62	59	56	49	50	47	44	43	40
10	I/O10L	I/O8L	I/O6L	I/O3L	1/O1L	ŪB∟	CEL	A13L	A10L	A 9L	Aer
	67	65		<u> </u>	57	53	52			41	39
09	I/O11L	I/O9L			GND	Vcc	R/WL			A7L	A5L
	69	68	1					1		38	37
80	I/O13L	I/O12L								A ₄ L	Азь
	72	71	73						33	35	34
07	1/O15L	I/O14L	Vcc			IDT7026	i		BUSYL	A1L	AoL
	75	70	74			32	31	36			
06	I/Oor	GND	GND		84-PIN PGA TOP VIEW						A ₂ L
	76	77	78		TOP VIEW					29	30
05	I/O1R	I/O2R	Vcc						A1R	Aor	BUSY
	79	80								26	27
04	1/O3R	1/O4R								AзR	A2F
	81	83	1		7	11	12	1		23	25
03	1/O5R	I/O7R			GND	GND	SEMR			A6R	A4R
	82	1	2	5	8	10	14	17	20	22	24
02	I/O6R	I/O9R	I/O10R	I/O13R	I/O15R	R/WR	Ū₿R	A12R	A9R	A7R	A ₅ R
	84	3	4	6	9	15	13	16	18	19	21
01	I/O8R	I/O11R	I/O12R	I/O14R	ŌĒR	LBR	CER	A13R	A11R	A ₁₀ R	A8R
1		В	C		E	F	G	' н	J	K	

DINI NIAMEC

Left Port	Right Port	Names		
CEL	CER	Chip Enable		
R∕ W L	R/ W R	Read/Write Enable		
<u>OE</u> L	ŌĒR	Output Enable		
A0L - A13L	A0R - A13R	Address		
I/O0L — I/O15L	I/OoR - I/O15R	Data Input/Output		
SEML	SEM _R	Semaphore Enable		
UB L	ŪBR	Upper Byte Select		
<u>LB</u> L	LBR	Lower Byte Select		
BUSYL	BUSYR	Busy Flag		
N	n/S	Master or Slave Select		
V	/cc	Power		
G	ND	Ground		

INTEGRATED DEVICE

NOTES:

1 All Vcc pins must be connected to power supply 2 All GND pins must be connected to ground supply

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TRUTH TABLE: NON-CONTENTION READ/WRITE CONTROL INTEGRATED DEVICE

	Outputs							Inpu		
Mode	1/00-7	1/08-15	SEM	<u>LB</u>	UB	OE .	R/W	CE		
Deselected Power Down	High-Z	Hıgh-Z	Н	X	Х	Х	Х	Н		
Both Bytes Deselected Power Down	High-Z	High-Z	Н	Н	Н	Х	Х	Х		
Vrite to Upper Byte Only	High-Z	DATAIN	Н	Н	L	Х	L	L		
Vrite to Lower Byte Only	DATAIN	High-Z	Н	L	Н	Х	L	L		
Vrite to Both Bytes	DATAIN	DATAIN	Н	L	L	Х	L	L		
Read Upper Byte Only	High-Z	DATAOUT	Н	Н	L	L	Н	L		
Read Lower Byte Only	DATAOUT	High-Z	Н	L	Н	L	Н	L		
Read Both Bytes	DATAOUT	DATAOUT	Н	L	L	L	Н	L		
Outputs Disabled	High-Z	High-Z	Х	Х	Х	Н	Х	Х		

NOTE:

1 AoL - A13L ≠ AoR - A13R

2939 tbl 02

TRUTH TABLE: SEMAPHORE READ/WRITE CONTROL

		lnp	uts			Out	outs	
CE	₽/₩	Œ	ŪΒ	EB	SEM	I/O8-15	I/O0-7	Mode
Н	Н	L	Х	Х	L	DATAOUT	DATAOUT	Read Data in Semaphore Flag
Х	Н	L	Н	Н	L	DATAOUT	DATAOUT	Read Data in Semaphore Flag
Н	£	Х	Х	Х	L	DATAIN	DATAIN	Write Dino into Semaphore Flag
Х	<i>F</i>	Х	H	Н	L	DATAIN	DATAIN	Write Dเทอ into Semaphore Flag
L	Х	Х	L	X	L		_	Not Allowed
Ĺ	X	Х	Х	L	Ĺ			Not Allowed

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Commercial	Military	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0 5 to +7 0	-0 5 to +7 0	V
Ta	Operating Temperature	0 to +70	-55 to +125	ô
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	ŷ
Тѕтс	Storage Temperature	-55 to +125	-65 to +150	ô
lout	DC Output Current	50	50	mA

NOTE:

2939 tbl 04

2 VTERM must not exceed Vcc + 0 5V.

RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE

Grade	Ambient Temperature	GND	Vcc
Military	-55°C to +125°C	VO	5 0V ± 10%
Commercial	0°C to +70°C	0V	5 0V ± 10%

2939 tbl 05

2939 tbl 03

RECOMMENDED DC OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	4.5	50	5.5	٧
GND	Supply Voltage	0	0	0	٧
ViH	Input High Voltage	22	_	6 0 ⁽²⁾	V
VIL	Input Low Voltage	-0 5 ⁽¹⁾	_	0.8	٧

NOTE:

2939 tbl 06

1 VIL \geq -3 0V for pulse width less than 20ns

2 VTERM must not exceed Vcc + 0 3V

CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit	
CIN	Input Capacitance	VIN = 0V	11	рF	
Соит	Output Capacitance	V OUT = 0V	11	pF	

NOTE:

2939 tbl 07

 This parameter is determined by device characterization but is not production tested

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Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

INTEGRATED DEVICE DC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE (Vcc = 5.0V ± 10%)

			IDT7	026S	סלדסו		
Symbol	Parameter	Test Conditions	Min.	Max.	Min.	Max.	Unit
Li	Input Leakage Current ⁽⁵⁾	Vcc = 5 5V, Vin = 0V to Vcc		10	_	5	μА
lco	Output Leakage Current	CE = VIH, VOUT = 0V to VCC	-	10	_	5	μА
Vol	Output Low Voltage	IOL = 4mA		0 4	_	0 4	٧
Vон	Output High Voltage	IOH = -4mA	2 4	_	2 4	I —	V

2939 tbl 08

DC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE(1) (Vcc = 5.0V ± 10%)

		Test			7026 COM'L	ONLY	7026	X35	
Symbol	Parameter	Condition	Versio	n	Тур. ⁽²⁾	Max.	Typ. ⁽²⁾	Max.	Unit
lcc	Dynamic Operating Current	CE ≤ VIL, Outputs Open SEM ≥ VIH	MIL	S L	_	_	160 160	480 410	mA
	(Both Ports Active)	$f = fMAX^{(3)}$	COM, F	S L	170 170	430 370	160 160	410 350	
ISB1	Standby Current (Both Ports — TTL	CER = CEL≥ VIH SEMR = SEML≥ VIH	MIL	S L			20 20	100 80	mA
	Level Inputs)	$f = fMAX^{(3)}$	COM'L	S L	25 25	85 60	20 20	85 60	
ISB2	Standby Current (One Port — TTL	CEL or CER≥ ViH Active Port Outputs Open	MIL	S L	_	_	95 95	350 300	mA
	Level Inputs)	f = fmax ⁽³⁾ SEMR = SEML≥ VIH	COM'L	S L	105 105	300 265	95 95	290 255	
ISB3	Full Standby Current (Both Ports — All	Both Ports CEL and CER ≥ Vcc - 0.2V	MIL	S L		_ _	10 02	35 12	mA
	CMOS Level Inputs)	VIN ≥ Vcc - 0 2V or VIN ≤ 0 2V, f = 0 ⁽⁴⁾ SEMR = SEML≥ Vcc - 0 2V	COM'L	S L	10 02	18 6	10	18 6	
ISB4	Full Standby Current (One Port — All CMOS Level Inputs)	One Port CEL or CER ≥ Vcc - 0 2V SEMR = SEML≥ Vcc - 0 2V	MIL	S L	_	_	90 90	310 260	mA
	Olvido Level Inputs)	Vin ≥ Vcc - 0.2V or	COM'L	S	100	275	90	265	1
		$ \begin{array}{l} \text{Vin} \leq 0 \text{ 2V} \\ \text{Active Port Outputs Open,} \\ f = \text{fmax}^{(3)} \\ \end{array} $		L	100	230	95	215	

NOTES:

- X in part numbers indicates power rating (S or L)
- Vcc = 5V, Ta = +25°C
- At f = fMax, address and control lines (except Output Enable) are cycling at the maximum frequency read cycle of 1/tnc, and using "AC Test Conditions" of input levels of GND to 3V
- f = 0 means no address or control lines change

MILITARY AND COMMERCIAL TEMPERATURE RANGES

INTEGRATED DEVICE DC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE⁽¹⁾(Continued) (Vcc = 5.0V ± 10%)

		Test	1			6X45		5X55	7026 MIL C	NLY	
Symbol	Parameter	Condition	Versio	n	Typ. ⁽²⁾	Max.	Typ. ⁽²⁾	Max.	Тур. ⁽²⁾	Max.	Unit
lcc	Dynamic Operating Current	CE ≤ VIL, Outputs Open SEM ≥ VIH	MIL.	S	155 155	480 410	150 150	475 400	140 140	470 395	mA
	(Both Ports Active)	f = fmax ⁽³⁾	COM'L	S L	155 155	410 350	150 150	400 340	_	_	
ISB1	Standby Current (Both Ports — TTL	CEL = CER≥ VIH SEMR = SEML≥ VIH	MIL	S	16 16	100 80	13 13	100 80	10 10	100 80	mA
	Level Inputs)	f = fmax ⁽³⁾	COM'L	S L	16 16	85 60	13 13	85 60	_		
Isa2	Standby Current (One Port — TTL	CER or CEL≥ VIH Active Port Outputs Open	MIL	S L	90 90	350 300	85 85	350 300	80 80	350 300	mA
	Level Inputs)	f = fmax ⁽³⁾ SEMR = SEML≥ Vih	COM'L	S L	90 90	290 250	85 85	290 250	_	_	
ISB3	Full Standby Current (Both Ports — All	Both Ports CEL and CER ≥ Vcc - 0 2V	MIL	S L	10 02	35 12	10 02	35 12	10 02	35 12	mA
	CMOS Level Inputs)	$\begin{aligned} & \text{Vin} \geq \text{Vcc} - 0.2\text{V or} \\ & \text{Vin} \leq 0.2\text{V}, \text{f} = 0^{(4)} \\ & \overline{\text{SEMr}} = \overline{\text{SEML}} \geq \text{Vcc} - 0.2\text{V} \end{aligned}$	COM'L.	S L	10 02	18 6	1.0 02	18 6	_	_	
ISB4	Full Standby Current (One Port — All CMOS Level Inputs)	One Port CEL or CER ≥ Vcc - 0 2V SEMR = SEML≥ Vcc - 0 2V	MIL	S L	85 85	310 260	80 80	310 260	75 75	310 260	mA
		$V_{IN} \ge V_{CC} - 0.2V$ or $V_{IN} \le 0.2V$ Active Port Outputs Open, $f = f_{MAX}^{(3)}$	COM'L	S L	85 85	265 215	80 80	265 215	_	_	

NOTES:

f = 0 means no address or control lines change

²⁹³⁹ tbl 10

X in part numbers indicates power rating (S or L)

VCc = 5V, TA = +25°C

Atf = fMAX, address and control lines (except Output Enable) are cycling at the maximum frequency read cycle of 1/tRC, and using "AC Test Conditions" of input levels of GND to 3V

MILITARY AND COMMERCIAL TEMPERATURE RANGES

AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	5ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figures 1 & 2
	2939 tbl 12

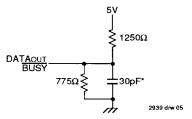


Figure 1. Output Load (5pF for tLz, tHz, twz, tow) * Including scope and jig.

AC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE⁽⁴⁾

			IDT7026X25 COM'L ONLY		IDT7026X35	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
READ CYCLE						
tRC	Read Cycle Time	25	_	35		ns
taa	Address Access Time	T —	25		35	лѕ
tACE	Chip Enable Access Time ⁽³⁾		25	_	35	ns
t ABE	Byte Enable Access Time ⁽³⁾		25		35	лѕ
t AOE	Output Enable Access Time		13		20	ns
t OH	Output Hold from Address Change	3	_	3	—	ns
tLZ	Output Low-Z Time ^(1, 2)	3	l –	3	-	ns
tHZ	Output High-Z Time ^(1, 2)	T -	15	_	15	ns
tPU	Chip Enable to Power Up Time ⁽²⁾	0	_	0		ns
t PD	Chip Disable to Power Down Time ⁽²⁾		50	_	50	ns
tsop	Semaphore Flag Update Pulse (OE or SEM)	12	_	15	<u> </u>	ns
1SAA	Semaphore Address Access Time	1 -	30	I —	40	ns

		IDT7026X45		5 IDT7026X55		IDT7026X70 MIL ONLY			
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit	
READ CYCLE									
tRC	Read Cycle Time	45		55		70	_	ns	
taa	Address Access Time	_	45		55	_	70	ns	
tACE	Chip Enable Access Time ⁽³⁾	_	45		55	_	70	ns	
tABE	Byte Enable Access Time ⁽³⁾		45	_	55	<u> </u>	70	ns	
taoe	Output Enable Access Time	_	25	_	30	<u> </u>	35	ns	
ton	Output Hold from Address Change	3		3	_	3		ns	
tLZ	Output Low-Z Time ^(1, 2)	3	_	3	_	3	l –	ns	
tHZ	Output High-Z Time ^(1, 2)	l –	20	<u> </u>	25		30	ns	
t PU	Chip Enable to Power Up Time ⁽²⁾	0	_	0	_	0	_	ns	
tPD	Chip Disable to Power Down Time ⁽²⁾	<u> </u>	50	_	50		50	ns	
tsop	Semaphore Flag Update Pulse (OE or SEM)	15		15	I —	15	_	ns	
tsaa	Semaphore Address Access Time	l –	50	_	60		75	ns	

NOTES:

2939 tbl 13

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Transition is measured ±500 mV from low- or high-impedance voltage with load (Figures 1 and 2).

This parameter is guaranteed but not tested

To access RAM, CE = LOW, UB or LB = LOW, SEM = HIGH 3

X in part numbers indicates power rating (S or L)

NOTES:

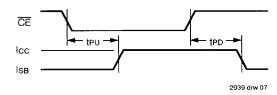
BUSYout

- 1 Timing depends on which signal is asserted last, OE, CE, LB, or UB
- 2 Timing depends on which signal is de-asserted first CE, OE, LB, or UB
- 3 tepp delay is required only in case where opposite port is completing a write operation to the same address location for simultaneous read operations BUSY has no relation to valid output data

t_{BDD} (3, 4)

- 4 Start of valid data depends on which timing becomes effective last tabe, tace, tace, tax or tedd
- 5 SEM = HIGH

TIMING OF POWER-UP POWER-DOWN



2939 drw 06

AC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE (5)

INTEGRATED DEVICE

			IDT7026X25 COM'L ONLY		IDT7026X35	
Symbol	Parameter		Max.	Min.	Max.	Unit
WRITE CYCLE						
twc	Write Cycle Time	25	_	35	_	ns
tew	Chip Enable to End-of-Write ⁽³⁾	20	T —	30		ns
taw	Address Valid to End-of-Write	20	T —	30	_	ns
tas	Address Set-up Time ⁽³⁾	0	l —	0		ns
twp	Write Pulse Width	20	T —	30	_	ns
twn	Write Recovery Time	0	_	0	_	ns
tow	Data Valid to End-of-Write	15	_	25		ns
tHZ	Output High-Z Time ^(1, 2)		15	_	15	ns
tDH	Data Hold Time ⁽⁴⁾	0	-	0		ns
twz	Write Enable to Output in High-Z ^(1, 2)		15	<u> </u>	15	ns
tow	Output Active from End-of-Write ^(1, 2, 4)	0	_	0	_	ns
tswrd	SEM Flag Write to Read Time	10	<u> </u>	10	_	ns
tsps	SEM Flag Contention Window	10	T —	10		ns

		IDT70	IDT7026X45		IDT7026X55		IDT7026X70 MIL. ONLY	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
WRITE C	YCLE							
twc	Write Cycle Time	45	_	55	_	70		ns
tew	Chip Enable to End-of-Write ⁽³⁾	40	_	45		50		ns
taw	Address Valid to End-of-Write	40	<u> </u>	45	_	50		ns
tas	Address Set-up Time ⁽³⁾	0	_	0	_	0	_	ns
twp	Write Pulse Width	35	_	40	_	50	-	ns
twn	Write Recovery Time	0		0	_	0	<u> </u>	ns
tow	Data Valid to End-of-Write	25	_	30		40		ns
tHZ	Output High-Z Time ^(1, 2)	_	20	I –	25		30	ns
tDH	Data Hold Time ⁽⁴⁾	0		0	T -	0	-	ns
twz	Write Eпable to Output in High-Z ^(1, 2)		20	_	25	<u> </u>	30	ns
tow	Output Active from End-of-Write ^(1, 2, 4)	0	<u> </u>	0		0	—	ns
tswrd	SEM Flag Write to Read Time	10	<u> </u>	10		10	T -	ns
tsps	SEM Flag Contention Window	10		10	—	10	1 —	ns

NOTES:

Transition is measured ±500mV from low- or high-impedance voltage with load (Figures 1 and 2)

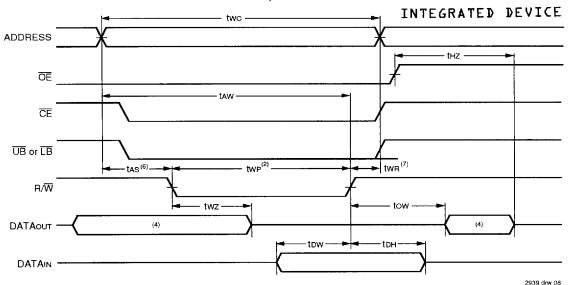
X in part numbers indicates power rating (S or L).

This parameter is guaranteed but not tested

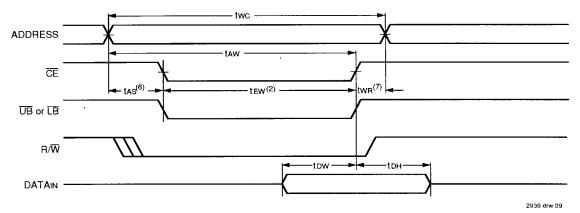
To access RAM, $\overline{CE} = LOW$, \overline{UB} or $\overline{LB} = LOW$, $\overline{SEM} = HIGH$ To access semaphore, $\overline{CE} = HIGH$ and $\overline{SEM} = LOW$ Either condition must be valid for the entire tew time

The specification for tori must be met by the device supplying write data to the RAM under all operating conditions. Although tori and tow values will vary over voltage and temperature, the actual ton will always be smaller than the actual tow

TIMING WAVEFORM OF WRITE CYCLE NO. 1, R/W CONTROLLED TIMING(1,3,5,8)



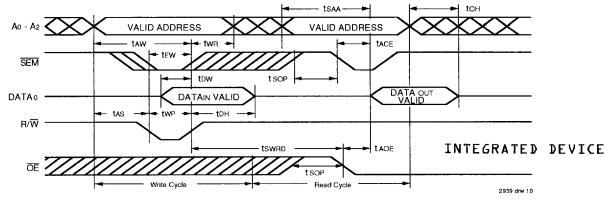
TIMING WAVEFORM OF WRITE CYCLE NO. 2, $\overline{\text{CE}}$, $\overline{\text{UB}}$, $\overline{\text{LB}}$ CONTROLLED TIMING^(1,3,5,8)



NOTES:

- R/W or CE or UB & LB must be HIGH during all address transitions
- A write occurs during the overlap (tew or twe) of a LOW $\overline{\text{UB}}$ or $\overline{\text{LB}}$ and a LOW $\overline{\text{CE}}$ and a LOW R/\overline{W} for memory array writing cycle two is measured from the earlier of $\overline{\text{CE}}$ or R/\overline{W} (or $\overline{\text{SEM}}$ or R/\overline{W}) going HIGH to the end of write cycle
- During this period, the I/O pins are in the output state and input signals must not be applied
- If the CE or SEM LOW transition occurs simultaneously with or after the R/W LOW transition, the outputs remain in the high-impedance state
- Timing depends on which enable signal is asserted last, CE, R/W or byte control
- Timing depends on which enable signal is de-asserted first, $\overline{\text{CE}}$, $\overline{\text{R/W}}$ or byte control
- If OE is LOW during R/W controlled write cycle, the write pulse width must be the larger of twp or (twz + tow) to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If OE is HIGH during an R/W controlled write cycle, this requirement does not apply and the write pulse can be as short as the specified two

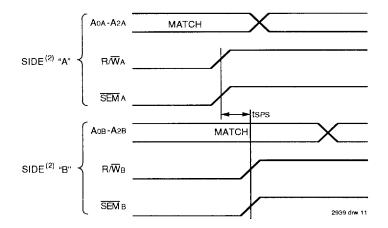
TIMING WAVEFORM OF SEMAPHORE READ AFTER WRITE TIMING, EITHER SIDE(1)



NOTE:

1 \overline{CE} = HIGH or \overline{UB} & \overline{LB} = HIGH for the duration of the above timing (both write and read cycle).

TIMING WAVEFORM OF SEMAPHORE WRITE CONTENTION(1,3,4)



NOTES:

- DOR = DOL = LOW, CER = CEL = HIGH, or both UB & LB = HIGH, Semaphore Flag is released from both sides (reads as ones from both sides) at cycle start
- "A" may be either left or right port "B" is the opposite port from "A"
- This parameter is measured from R/Wa or SEMa going HIGH to R/We or SEMe going HIGH
- If tars is not satisfied, the semaphore will fall positively to one side or the other, but there is no guarantee which side will obtain the flag

AC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE⁽⁶⁾

INTEGRATED DEVICE

		IDT7026X25 COM'L ONLY		IDT7026X35		
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
BUSY TIM	IING (M/S=H)					
tbaa	BUSY Access Time from Address Match	_	25	_	35	ns
tBDA	BUSY Disable Time from Address Not Matched		20	-	30	ns
1BAC	BUSY Access Time from Chip Enable LOW		20	_	30	ns
tBDC	BUSY Disable Time from Chip Enable HIGH		17	_	25	ns
taps	Arbitration Priority Set-up Time ⁽²⁾	5	_	5		ns
tBDD	BUSY Disable to Valid Data ⁽³⁾	—	Note 3	_	Note 3	ns
BUSY TIM	IING (M/S=L)					
twB	BUSY Input to Write ⁽⁴⁾	0	_	0	_	ns
twн	Write Hold After BUSY ⁽⁵⁾	17	_	25	I —	ns
PORT-TO	-PORT DELAY TIMING					
twdd	Write Pulse to Data Delay ⁽¹⁾		50		60	ns
todo	Write Data Valid to Read Data Delay ⁽¹⁾	_	35	_	45	ns

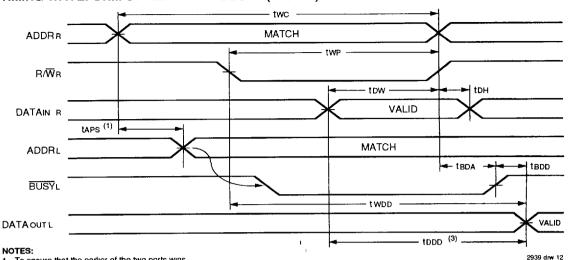
		IDT7026X45		IDT7026X55		IDT7026X70 MIL. ONLY			
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit	
BUSY TIM	/ING (M/S = H)								
tBAA	tBAA BUSY Access Time from Address Match		35	—	45	_	45	ns	
tBDA	BUSY Disable Time from Address Not Matched		30		40	<u> </u>	40	ns	
tBAC	BUSY Access Time from Chip Enable LOW	_	30		40		40	ns	
tBDC	BUSY Disable Time from Chip Enable HIGH	_	25	_	35	_	35	ns	
taps	Arbitration Priority Set-up Time ⁽²⁾	5		5	<u> </u>	5		ns	
tBDD	BUSY Disable to Valid Data ⁽³⁾	_	Note 3	_	Note 3	_	Note 3	ns	
BUSY TIM	AING (M/S = L)								
tws	BUSY Input to Write ⁽⁴⁾	0	_	0		0	_	ns	
twн	Write Hold After BUSY ⁽⁵⁾	25	_	25		25	l –	ns	
PORT-TO	PORT-TO-PORT DELAY TIMING								
twdd	Write Pulse to Data Delay ⁽¹⁾	_	70	-	80	_	95	ns	
tDDD	Write Data Valid to Read Data Delay ⁽¹⁾	_	55	-	65	_	80	ns	

NOTES:

- 2939 tbl 15 1. Port-to-port delay through RAM cells from writing port to reading port, refer to "Timing Waveform of Read With BUSY (M/S = HIGH)" or "Timing Waveform of Write With Port-To-Port Delay (M/S=LOW)"
- To ensure that the earlier of the two ports wins
- 3. tbbb is a calculated parameter and is the greater of 0, twbb twp (actual) or tbbb tbw (actual).
- To ensure that the write cycle is inhibited during contention
- 5. To ensure that a write cycle is completed after contention.6 "x" is part numbers indicates power rating (S or L)



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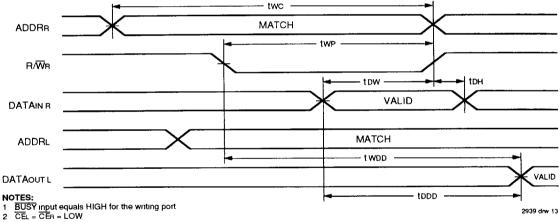


1. To ensure that the earlier of the two ports wins

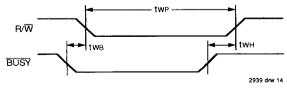
CEL = CER = LOW

3. \overline{OE} = LOW for the reading port.

TIMING WAVEFORM OF WRITE WITH PORT-TO-PORT DELAY^(1,2) (M/ \overline{S} = L)



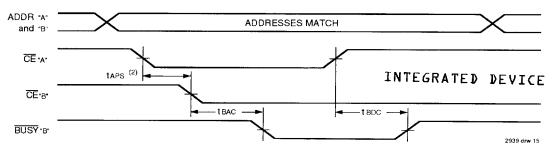
TIMING WAVEFORM OF SLAVE WRITE $(M/\overline{S} = L)$



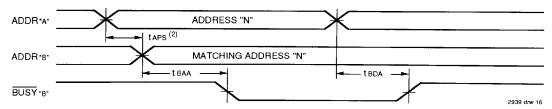
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WAVEFORM OF BUSY ARBITRATION CONTROLLED BY CE TIMING(1) (M/S = H)



WAVEFORM OF BUSY ARBITRATION CYCLE CONTROLLED BY ADDRESS MATCH $TIMING^{(1)}(M/\overline{S} = H)$



NOTES:

- 1 All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from "A"
- 2 If tAPS is not satisfied, the busy signal will be asserted on one side or another but there is no guarantee on which side busy will be asserted

TRUTH TABLE I — EXAMPLE OF SEMAPHORE PROCUREMENT SEQUENCE(1)

Functions	Do - D15 Left	Do - D15 Right	Status
No Action	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Right Port Writes "0" to Semaphore	0	1	No change Right side has no write access to semaphore
Left Port Writes "1" to Semaphore	1	0	Right port obtains semaphore token
Left Port Writes "0" to Semaphore	1	0	No change Left port has no write access to semaphore
Right Port Writes "1" to Semaphore	0	1	Left port obtains semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free
Right Port Writes "0" to Semaphore	1	0	Right port has semaphore token
Right Port Writes "1" to Semaphore	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free

NOTE:

¹ This table denotes a sequence of events for only one of the eight semaphores on the IDT7026

TRUTH TABLE II — ADDRESS BUSY ARBITRATION

	Inp	uts	Out	puts	
CEL	CĒR	A0L-A13L A0R-A13R	BUSYL ⁽¹⁾	BUSYR ⁽¹⁾	Function
Х	Χ	NO MATCH	Н	Н	Normal
Н	Х	MATCH	Н	H	Normal
Х	Н	MATCH	н	Н	Normal
L	L	MATCH	(2)	(2)	Write Inhibit ⁽³⁾

NOTES:

- Pins BUSYL and BUSYR are both outputs when the part is configured as a master Both are inputs when configured as a slave BUSYx outputs on the IDT7026 are push pull, not open drain outputs. On slaves the BUSYx input internally inhibits writes
- LOW if the inputs to the opposite port were stable prior to the address and enable inputs of this port. HIGH if the inputs to the opposite port became stable after the address and enable inputs of this port. If taps is not met, either BUSYL or BUSYR = LOW will result BUSYL and BUSYR outputs cannot be LOW simultaneously
- Writes to the left port are internally ignored when BUSYL outputs are driving LOW regardless of actual logic level on the pin Writes to the right port are internally ignored when BUSYs outputs are driving LOW regardless of actual logic level on the pin

FUNCTIONAL DESCRIPTION

The IDT7026 provides two ports with separate control. address and I/O pins that permit independent access for reads or writes to any location in memory. The IDT7026 has an automatic power down feature controlled by $\overline{\text{CE}}$. The $\overline{\text{CE}}$ controls on-chip power down circuitry that permits the respective port to go into a standby mode when not selected (CE HIGH). When a port is enabled, access to the entire memory array is permitted.

BUSY LOGIC

Busy Logic provides a hardware indication that both ports of the RAM have accessed the same location at the same time. It also allows one of the two accesses to proceed and signals the other side that the RAM is "busy". The busy pin can then be used to stall the access until the operation on the other side is completed. If a write operation has been attempted from the side that receives a busy indication, the write signal is gated internally to prevent the write from proceeding.

The use of busy logic is not required or desirable for all applications. In some cases it may be useful to logically OR the busy outputs together and use any busy indication as an interrupt source to flag the event of an illegal or illogical operation. If the write inhibit function of busy logic is not desirable, the busy logic can be disabled by placing the part in slave mode with the M/S pin. Once in slave mode the BUSY pin operates solely as a write inhibit input pin. Normal operation can be programmed by tying the BUSY pins HIGH. If desired, unintended write operations can be prevented to a port by tying the busy pin for that port LOW.

The busy outputs on the IDT 7026 RAM in master mode, are push-pull type outputs and do not require pull up resistors to operate. If these RAMs are being expanded in depth, then the busy indication for the resulting array requires the use of an external AND gate.

WIDTH EXPANSION WITH BUSY LOGIC MASTER/SLAVE ARRAYS

When expanding an IDT7026 RAM array in width while using busy logic, one master part is used to decide which side of the RAM array will receive a busy indication, and to output that indication. Any number of slaves to be addressed in the same address range as the master, use the busy signal as a write inhibit signal. Thus on the IDT7026 RAM the busy pin is an output if the part is used as a master $(M/\overline{S}pin = H)$, and the busy pin is an input if the part used as a slave $(M/\overline{S}pin = L)$ as shown in Figure 3.

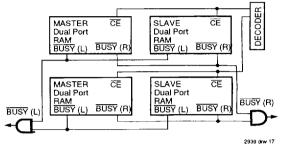


Figure 3. Busy and chip enable routing for both width and depth expansion with IDT7026 RAMs.

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If two or more master parts were used when expanding in width, a split decision could result with one master indicating busy on one side of the array and another master indicating busy on one other side of the array. This would inhibit the write operations from one port for part of a word and inhibit the write operations from the other port for the other part of the word.

The busy arbitration, on a master, is based on the chip enable and address signals only. It ignores whether an access is a read or write. In a master/slave array, both address and chip enable must be valid long enough for a busy flag to be output from the master before the actual write pulse can be initiated with either the R/W signal or the byte enables. Failure to observe this timing can result in a glitched internal write inhibit signal and corrupted data in the slave.

SEMAPHORES

The IDT7026 is an extremely fast Dual-Port 16K x 16 CMOS Static RAM with an additional 8 address locations dedicated to binary semaphore flags. These flags allow either processor on the left or right side of the Dual-Port RAM to claim a privilege over the other processor for functions defined by the system designer's software. As an example, the semaphore can be used by one processor to inhibit the other from accessing a portion of the Dual-Port RAM or any other shared resource.

The Dual-Port RAM features a fast access time, and both ports are completely independent of each other. This means that the activity on the left port in no way slows the access time of the right port. Both ports are identical in function to standard

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CMOS Static RAM and can be read from, or written to, at the same time with the only possible conflict arising from the simultaneous writing of, or a simultaneous READ/WRITE of, a non-semaphore location. Semaphores are protected against such ambiguous situations and may be used by the system program to avoid any conflicts in the non-semaphore portion of the Dual-Port RAM. These devices have an automatic power-down feature controlled by $\overline{\text{CE}}$, the Dual-Port RAM enable, and $\overline{\text{SEM}}$, the semaphore enable. The $\overline{\text{CE}}$ and $\overline{\text{SEM}}$ pins control on-chip power down circuitry that permits the respective port to go into standby mode when not selected. This is the condition which is shown in Truth Table where $\overline{\text{CE}}$ and $\overline{\text{SEM}}$ are both HIGH.

Systems which can best use the IDT7026 contain multiple processors or controllers and are typically very high-speed systems which are software controlled or software intensive. These systems can benefit from a performance increase offered by the IDT7026's hardware semaphores, which provide a lockout mechanism without requiring complex programming.

Software handshaking between processors offers the maximum in system flexibility by permitting shared resources to be allocated in varying configurations. The IDT7026 does not use its semaphore flags to control any resources through hardware, thus allowing the system designer total flexibility in system architecture.

An advantage of using semaphores rather than the more common methods of hardware arbitration is that wait states are never incurred in either processor. This can prove to be a major advantage in very high-speed systems.

HOW THE SEMAPHORE FLAGS WORK

The semaphore logic is a set of eight latches which are independent of the Dual-Port RAM. These latches can be used to pass a flag, or token, from one port to the other to indicate that a shared resource is in use. The semaphores provide a hardware assist for a use assignment method called "Token Passing Allocation." In this method, the state of a semaphore latch is used as a token indicating that shared resource is in use. If the left processor wants to use this resource, it requests the token by setting the latch. This processor then verifies its success in setting the latch by reading it. If it was successful, it proceeds to assume control over the shared resource. If it was not successful in setting the latch, it determines that the right side processor has set the latch first, has the token and is using the shared resource. The left processor can then either repeatedly request that semaphore's status or remove its request for that semaphore to perform another task and occasionally attempt again to gain control of the token via the set and test sequence. Once the right side has relinquished the token, the left side should succeed in gaining control.

The semaphore flags are active LOW. A token is requested by writing a zero into a semaphore latch and is released when the same side writes a one to that latch.

The eight semaphore flags reside within the IDT7026 in a separate memory space from the Dual-Port RAM. This

address space is accessed by placing a low input on the \overline{SEM} pin (which acts as a chip select for the semaphore flags) and using the other control pins (Address, \overline{OE} , and R/\overline{W}) as they would be used in accessing a standard Static RAM. Each of the flags has a unique address which can be accessed by either side through address pins A0 – A2. When accessing the semaphores, none of the other address pins has any effect.

When writing to a semaphore, only data pin Do is used. If a low level is written into an unused semaphore location, that flag will be set to a zero on that side and a one on the other side (see Table III). That semaphore can now only be modified by the side showing the zero. When a one is written into the same location from the same side, the flag will be set to a one for both sides (unless a semaphore request from the other side is pending) and then can be written to by both sides. The fact that the side which is able to write a zero into a semaphore subsequently locks out writes from the other side is what makes semaphore flags useful in interprocessor communications. (A thorough discussing on the use of this feature follows shortly.) A zero written into the same location from the other side will be stored in the semaphore request latch for that side until the semaphore is freed by the first side.

When a semaphore flag is read, its value is spread into all data bits so that a flag that is a one reads as a one in all data bits and a flag containing a zero reads as all zeros. The read value is latched into one side's output register when that side's semaphore select (\overline{SEM}) and output enable (\overline{OE}) signals go active. This serves to disallow the semaphore from changing state in the middle of a read cycle due to a write cycle from the other side. Because of this latch, a repeated read of a semaphore in a test loop must cause either signal $(\overline{SEM}$ or $\overline{OE})$ to go inactive or the output will never change.

A sequence WRITE/READ must be used by the semaphore in order to guarantee that no system level contention will occur. A processor requests access to shared resources by attempting to write a zero into a semaphore location. If the semaphore is already in use, the semaphore request latch will contain a zero, yet the semaphore flag will appear as one, a fact which the processor will verify by the subsequent read (see Table III). As an example, assume a processor writes a zero to the left port at a free semaphore location. On a subsequent read, the processor will verify that it has written successfully to that location and will assume control over the resource in question. Meanwhile, if a processor on the right side attempts to write a zero to the same semaphore flag it will fail, as will be verified by the fact that a one will be read from that semaphore on the right side during subsequent read. Had a sequence of READ/WRITE been used instead, system contention problems could have occurred during the gap between the read and write cycles.

It is important to note that a failed semaphore request must be followed by either repeated reads or by writing a one into the same location. The reason for this is easily understood by looking at the simple logic diagram of the semaphore flag in Figure 4. Two semaphore request latches feed into a semaphore flag. Whichever latch is first to present a zero to the semaphore flag will force its side of the semaphore flag LOW and the other side HIGH. This condition will continue until a

2939 drw 18 Figure 4. IDT7026 Semaphore Logic

one is written to the same semaphore request latch. Should the other side's semaphore request latch have been written to a zero in the meantime, the semaphore flag will flip over to the other side as soon as a one is written into the first side's request latch. The second side's flag will now stay LOW until its semaphore request latch is written to a one. From this it is easy to understand that, if a semaphore is requested and the processor which requested it no longer needs the resource, the entire system can hang up until a one is written into that semaphore request latch.

The critical case of semaphore timing is when both sides request a single token by attempting to write a zero into it at the same time. The semaphore logic is specially designed to resolve this problem. If simultaneous requests are made, the logic quarantees that only one side receives the token. If one side is earlier than the other in making the request, the first side to make the request will receive the token. If both requests arrive at the same time, the assignment will be arbitrarily made to one port or the other.

One caution that should be noted when using semaphores is that semaphores alone do not guarantee that access to a resource is secure. As with any powerful programming technique, if semaphores are misused or misinterpreted, a software error can easily happen.

Initialization of the semaphores is not automatic and must be handled via the initialization program at power-up. Since any semaphore request flag which contains a zero must be reset to a one, all semaphores on both sides should have a one written into them at initialization from both sides to assure that they will be free when needed.

USING SEMAPHORES—SOME EXAMPLES

Perhaps the simplest application of semaphores is their application as resource markers for the IDT7026's Dual-Port RAM. Say the 16K x 16 RAM was to be divided into two 8K x 16 blocks which were to be dedicated at any one time to servicing either the left or right port. Semaphore 0 could be used to indicate the side which would control the lower section of memory, and Semaphore 1 could be defined as the indicator for the upper section of memory.

To take a resource, in this example the lower 8K of

Dual-Port RAM, the processor on the left port could write and then read a zero in to Semaphore 0. If this task were successfully completed (a zero was read back rather than a one), the left processor would assume control of the lower 8K. Meanwhile the right processor was attempting to gain control of the resource after the left processor, it would read back a one in response to the zero it had attempted to write into Semaphore 0. At this point, the software could choose to try and gain control of the second 8K section by writing, then reading a zero into Semaphore 1. If it succeeded in gaining control, it would lock out the left side.

Once the left side was finished with its task, it would write a one to Semaphore 0 and may then try to gain access to Semaphore 1. If Semaphore 1 was still occupied by the right side, the left side could undo its semaphore request and perform other tasks until it was able to write, then read a zero into Semaphore 1. If the right processor performs a similar task with Semaphore 0, this protocol would allow the two processors to swap 8K blocks of Dual-Port RAM with each other.

The blocks do not have to be any particular size and can even be variable, depending upon the complexity of the software using the semaphore flags. All eight semaphores could be used to divide the Dual-Port RAM or other shared resources into eight parts. Semaphores can even be assigned different meanings on different sides rather than being given a common meaning as was shown in the example above.

Semaphores are a useful form of arbitration in systems like disk interfaces where the CPU must be locked out of a section of memory during a transfer and the I/O device cannot tolerate any wait states. With the use of semaphores, once the two devices has determined which memory area was "off-limits" to the CPU, both the CPU and the I/O devices could access their assigned portions of memory continuously without any wait

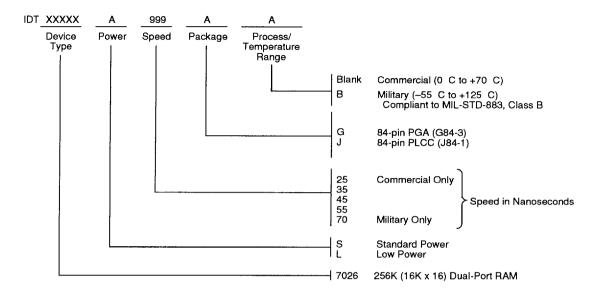
Semaphores are also useful in applications where no memory "WAIT" state is available on one or both sides. Once a semaphore handshake has been performed, both processors can access their assigned RAM segments at full speed.

Another application is in the area of complex data structures. In this case, block arbitration is very important. For this application one processor may be responsible for building and updating a data structure. The other processor then reads and interprets that data structure. If the interpreting processor reads an incomplete data structure, a major error condition may exist. Therefore, some sort of arbitration must be used between the two different processors. The building processor arbitrates for the block, locks it and then is able to go in and update the data structure. When the update is completed, the data structure block is released. This allows the interpreting processor to come back and read the complete data structure, thereby guaranteeing a consistent data structure.

ORDERING INFORMATION

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